Multilayer Ceramic Chip Capacitors

C3216X8L0G156M160AC









TDK item description C3216X8L0G156MT****

Applications	Commercial Grade	
	Please refer to Part No. <u>CGA5L1X8L0G156M160AC</u> for Automotive use.	
Feature	150°C High Temperature Application	
Series	C3216 [EIA 1206]	
Status	Production	



Size		
Length(L)	3.20mm +0.30,-0.10mm	
Width(W)	1.60mm +0.30,-0.10mm	
Thickness(T)	1.60mm +0.30,-0.10mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	1.00mm Min.	
Recommended Land Pattern (PA)	2.10mm to 2.50mm(Flow Soldering)	
Recommended Land Fattern (FA)	2.00mm to 2.40mm(Reflow Soldering)	
Recommended Land Pattern (PB)	1.10mm to 1.30mm(Flow Soldering)	
Recommended Land Fattern (FB)	1.00mm to 1.20mm(Reflow Soldering)	
Recommended Land Pattern (PC)	1.00mm to 1.30mm(Flow Soldering)	
neconfinenced Land Factor (FC)	1.10mm to 1.60mm(Reflow Soldering)	

Electrical Characteristics		
Capacitance	15μF ±20%	
Rated Voltage	4VDC	
Temperature Characteristic	X8L(+15,-40%)	
Dissipation Factor (Max.)	7.5%	
Insulation Resistance (Min.)	6ΜΩ	

Other	
Soldaring Mathad	Wave (Flow)
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

[!] Images are for reference only and show exemplary products.

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[!] All specifications are subject to change without notice.

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Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

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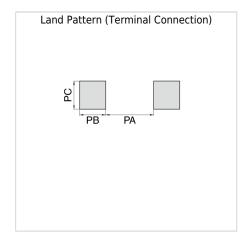








Associated Images



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